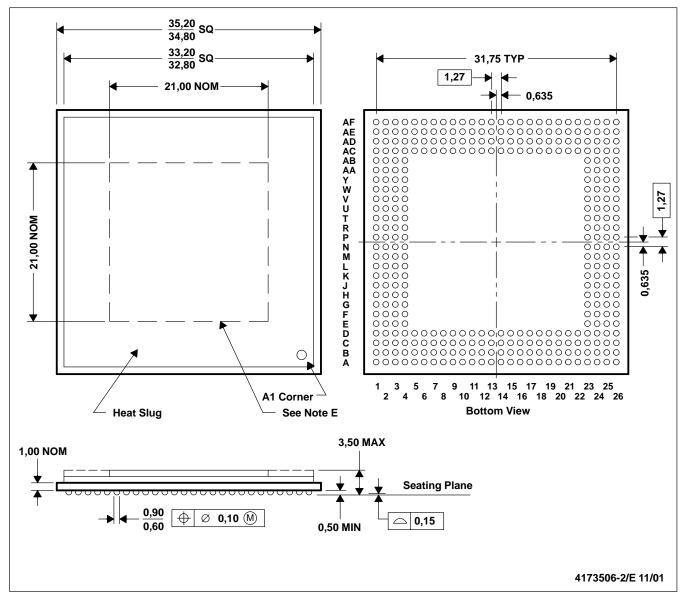
GJC (S-PBGA-N352)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Thermally enhanced plastic package with heat slug (HSL).
- D. Flip chip application only
- E. Possible protrusion in this area, but within 3,50 max package height specification
- F. Falls within JEDEC MO-151/BAR-2

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